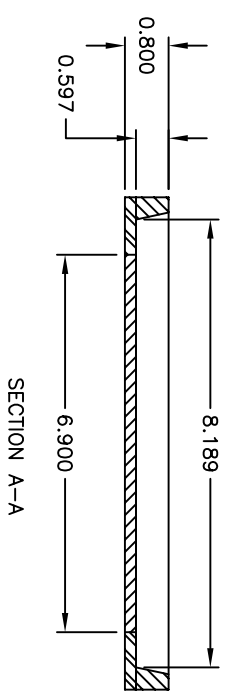
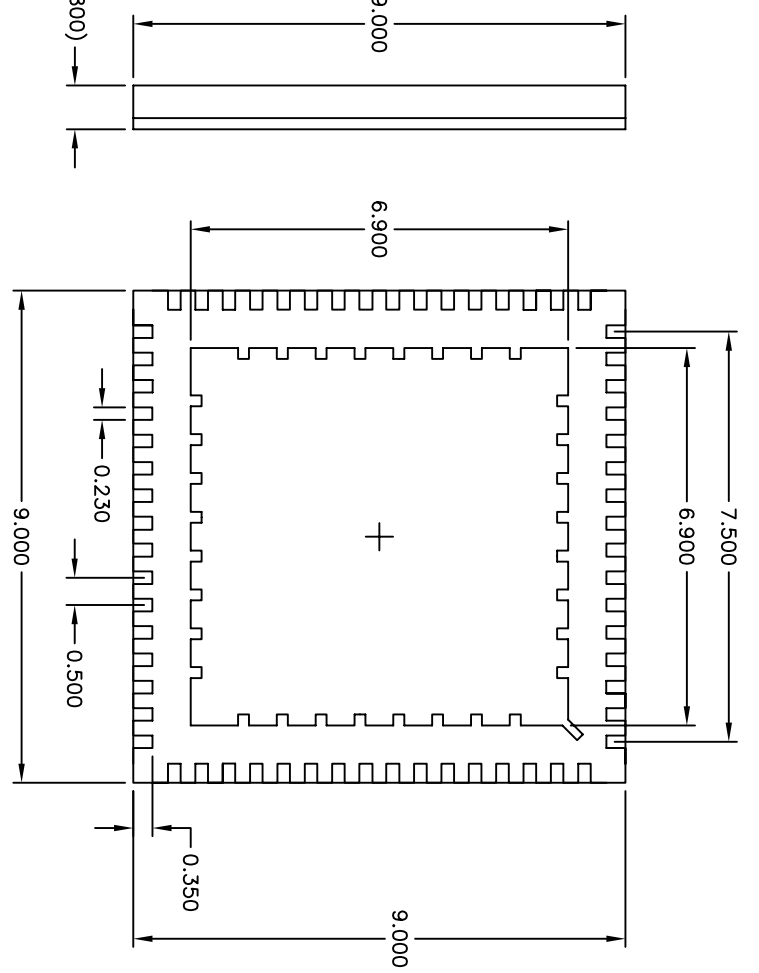
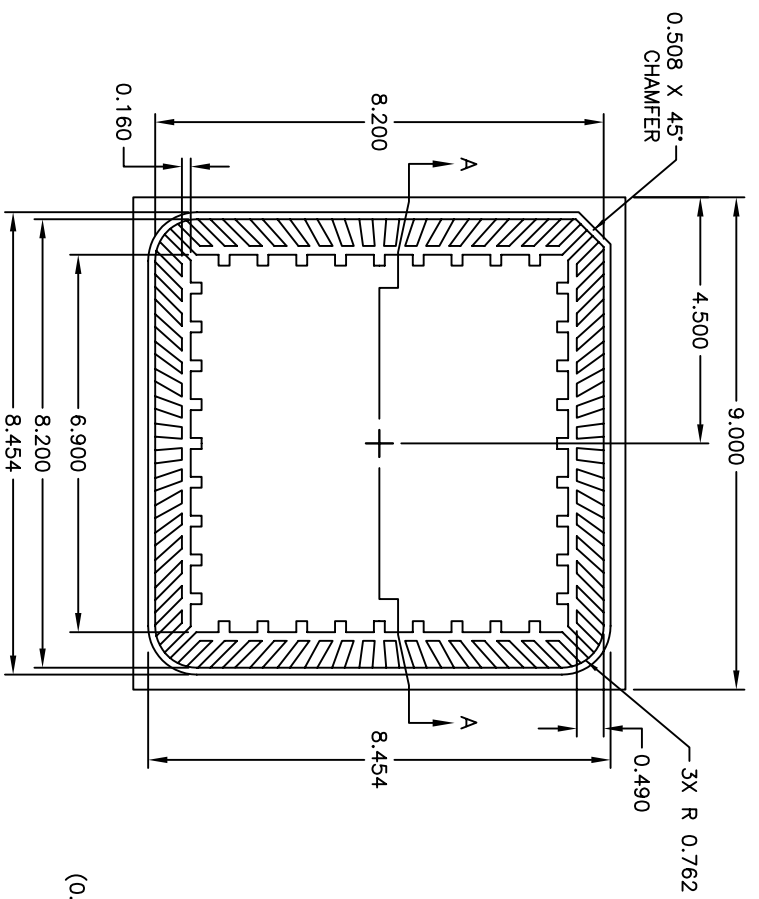


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| REVISIONS | | | |
|-----------|----------|--------------------|------------|
| ECN NO. | DATE | DESCRIPTION | APPROVED |
| 10638 | 04/01/06 | PRODUCTION RELEASE | D.BENANDIO |



- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEAD FRAME: COPPER, 194 FH.
 3. LEAD FINISH: FULL GOLD PLATE.
 4. FRAME THICKNESS: 0.2030 ±.0076
 5. DIE PAD: 6.900 X 6.900
 6. JEDEC OUTLINE: MO-220.



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS
 TOLERANCES ARE: XXXX ± 0.15 XXXX ± 0.10 ANGLES: ± 1°
 DO NOT SCALE DRAWING

| | | | |
|----------|--------------|------|----------|
| DRAWN BY | W. GRIFFITTS | DATE | 04/01/06 |
| APP BY | P. FLASKERUD | DATE | 04/01/06 |
| CUSTOMER | --- | | |

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| | | |
|-------|------------------------|-----|
| SIZE | PART NO. | REV |
| A | MLP9X9-64-OP-01 | 1 |
| SCALE | NONE | |
| FILE | MLP9X9-64-OP-01-R1.DWG | |
| SHEET | 1 OF 1 | |

2

1